

# DATA SHEET

# SKY67221-11: 1.6-2.1 GHz Low-Noise Amplifier Module

# **Applications**

- GSM, CDMA, UMTS, WCDMA, and LTE systems
- Cellular infrastructure
- Ultra low-noise systems

## **Features**

- Requires only one external component
- Optimized for 1.6 to 2.1 GHz operation
- Noise Figure: 0.90 dB typical @ 1.95 GHz
- Gain: 18.6 dB typical @ 1.95 GHz
- Input return loss: >25 dB typical @ 1.95 GHz
- Operating voltage range: 3.3 to 5.0 V
- Adjustable supply current: 30 to 120 mA
- High linearity IIP3: +18.4 dBm typical @ 1.95 GHz
- MCM (16-pin, 4 x 4 mm) package (MSL3, 260 °C per JEDEC J-STD-020) package



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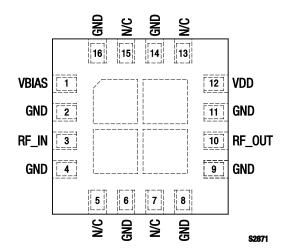


Figure 2. SKY67221-11 Pinout – 16-Pin MCM Package (Top View)

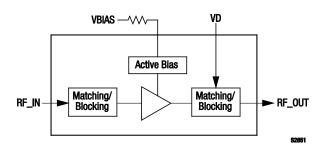


Figure 1. SKY67221-11 LNA Block Diagram

### **Description**

The SKY67221-11 is a high performance, Low-Noise Amplifier (LNA) designed for use in 1.6 to 2.1 GHz wireless infrastructure applications. The device consists of a single high linearity, GaAs pHEMT LNA and all associated matching components. The only external component necessary for proper operation is an external resistor, used to set the DC current. The device is also completely DC bypassed.

The package design nearly eliminates external surface mount components, greatly reduces printed circuit board area, and offers low thermal resistance for enhanced Mean Time Between Failures (MTBFs).

For optimum performance in the following frequency ranges, refer to the following product Data Sheets (all devices are pin-to-pin compatible with the SKY67221-11):

- 0.4 GHz to 0.7 GHz: SKY67215-11 (document #201842)
- 0.7 GHz to 1.2 GHz: SKY67216-11 (document #201808)
- 2.2 GHz to 3.0 GHz: SKY67226-11 (document #201841)

The SKY67221-11 is packaged in a 16-pin, 4 x 4 mm Multi-Chip Module (MCM). A block diagram of the SKY67221-11 is shown in Figure 1. The device package and pinout are shown in Figure 2.

# **Electrical and Mechanical Specifications**

Signal pin assignments and functional pin descriptions are described in Table 1. The absolute maximum ratings of the SKY67221-11 are provided in Table 2. Electrical specifications are provided in Tables 3, 4, and 5.

Typical performance characteristics of the SKY67221-11 are illustrated in Figures 3 through 24 (85 mA supply current).

## **Package and Handling Information**

Since the device package is sensitive to moisture absorption, it is baked and vacuum packed before shipping. Instructions on the shipping container label regarding exposure to moisture after the container seal is broken must be followed. Otherwise, problems related to moisture absorption may occur when the part is subjected to high temperature during solder assembly.

The SKY67221-11 is rated to Moisture Sensitivity Level 3 (MSL3) at 260 °C. It can be used for lead or lead-free soldering. For additional information, refer to the Skyworks Application Note *PCB Design and SMT Assembly/Rework Guidelines for MCM-L Packages*, document number 101752.

Care must be taken when attaching this product, whether it is done manually or in a production solder reflow environment. Production quantities of this product are shipped in a standard tape and reel format.

Pin #	Name	Description	Pin #	Name	Description
1	VBIAS	Low current bias for amplifier. External resistor sets current consumption.	9	GND	Ground
2	GND	Ground	10	RF_OUT	RF output, AC coupled. No external components required.
3	RF_IN	RF input, AC coupled. No external components required.	11	GND	Ground
4	GND	Ground	12	VDD	High current amplifier bias connection. No external bypassing required.
5	N/C	No connection	13	N/C	No connection
6	GND	Ground	14	GND	Ground
7	N/C	No connection	15	N/C	No connection
8	GND	Ground	16	GND	Ground

#### Table 1. SKY67221-11 Signal Descriptions

#### **Table 2. Absolute Maximum Ratings**

Parameter	Symbol	Minimum	Maximum	Units
Supply voltage	Vdd		5.5	V
RF input power	Pin		+20	dBm
Channel temperature	Тсн		150	°C
Operating temperature	Та	-55	+100	°C
Storage temperature	Тята	-65	+150	°C
Thermal resistance	OlO		68.8	°C/W

Note: Exposure to maximum rating conditions for extended periods may reduce device reliability. There is no damage to device with only one parameter set at the limit and all other parameters set at or below their nominal value. Exceeding any of the limits listed here may result in permanent damage to the device.

*CAUTION*: Although this device is designed to be as robust as possible, Electrostatic Discharge (ESD) can damage this device. This device must be protected at all times from ESD. Static charges may easily produce potentials of several kilovolts on the human body or equipment, which can discharge without detection. Industry-standard ESD precautions should be used at all times. The SKY67221-11 ESD threshold level is 500 VDC using Human Body Model (HBM) testing (Class 1B), 50 VDC using Man-Machine (MM) model testing (Class A), and 1000 VDC using Charged Device Model (CDM) testing (Class IV).

Parameter	Symbol	Test Conditions	Minimum	Typical	Maximum	Units
RF Specifications						
Noise Figure (Note 4)	NF	@ 1.95 GHz		0.9	1.2	dB
Small signal gain	S21	@ 1.95 GHz	17.1	18.6		dB
Input return loss	S11	@ 1.95 GHz	15.5	27.0		dB
Output return loss	S22	@ 1.95 GHz	10.5	14.5		dB
Reverse isolation	S12	@ 1.95 GHz	30.5	32.5		dB
$ \begin{array}{c} 3^{rd} \mbox{ Order Input Intercept Point } \\ IIP3 \\ \Delta f = 1 \mbox{ MHz}, \\ P_{IN} = -20 \mbox{ dBm/tone } \end{array} $		+15.4	+18.4		dBm	
3 <sup>rd</sup> Order Output Intercept Point	OIP3	@ 1.95 GHz, $\Delta f = 1$ MHz, $P_{IN} = -20$ dBm/tone	+34	+37		dBm
Input 1dB Compression Point	IP1dB	@ 1.95 GHz	+1.1	+3.1		dBm
Output 1dB Compression Point	0P1dB	@ 1.95 GHz	+18.7	+20.7		dBm
Stability (Note 3)	μ1, μ2, Κ, Β	Up to 18 GHz, –40 °C to +85 °C		>1		-
DC Specifications						
Supply voltage	Vdd			5		V
Quiescent current	loo	RBIAS = $6.8 \text{ k}\Omega$		85		mA

#### Table 3. SKY67221-11 Electrical Characteristics (Note 1) (Note 2) (Note 3)

(VDD = VBIAS = 5 V Nominal, IDD = 85 mA, TA = +25 °C, Characteristic Impedance [Zo] = 50 Ω, Unless Otherwise Noted)

Note 1: Performance is guaranteed only under the conditions listed in this Table.

Note 2: Circuit topology optimized for best compromise between NF, S11, IIP3, and IP1dB.

Note 3: Applies to typical application circuit and components shown in Figure 26.

Note 4: Loss from input SMA connector and Evaluation Board up to pin 3 of device has been de-embedded (0.04 dB @ 1.95 GHz) from the NF measurement.

Table 4. SKY67221-11 Electrical Characteristics (Note 1) (Note 2) (Note 3)					
(VDD = VBIAS = 5 V Nominal, IDD = 105 mA, TA = +25 °C, Characteristic Impedance [Zo] = 50 $\Omega$ , Unless Otherwise Noted)					

Parameter	Symbol	Test Conditions	Minimum	Typical	Maximum	Units
RF Specifications	·					
Noise Figure (Note 4)	NF	@ 1.60 GHz @ 1.95 GHz @ 2.10 GHz		0.80 0.91 1.05		dB dB dB
Small signal gain	S21	@ 1.60 GHz @ 1.95 GHz @ 2.10 GHz		20.1 19.3 18.4		dB dB dB
Input return loss	S11	@ 1.60 GHz @ 1.95 GHz @ 2.10 GHz		10 28 16		dB dB dB
Output return loss	S22	@ 1.60 GHz @ 1.95 GHz @ 2.10 GHz		10.5 13.9 12.6		dB dB dB
Reverse isolation	S12	@ 1.60 GHz @ 1.95 GHz @ 2.10 GHz		34.0 32.5 33.0		dB dB dB
3 <sup>rd</sup> Order Input Intercept Point	IIP3	$\Delta f = 1$ MHz, P <sub>IN</sub> = -20 dBm/tone: @ 1.60 GHz @ 1.95 GHz		+17.4 +18.7		dBm dBm
3 <sup>rd</sup> Order Output Intercept Point	OIP3	@ 2.10 GHz $\Delta f = 1$ MHz, Pℕ = -20 dBm/tone: @ 1.60 GHz @ 1.95 GHz @ 2.10 GHz		+19.4 +37.5 +38.0 +37.8		dBm dBm dBm dBm
Input 1dB Compression Point	IP1dB	@ 1.60 GHz @ 1.95 GHz @ 2.10 GHz		+2.4 +3.1 +4.4		dBm dBm dBm
Output 1dB Compression Point	OP1dB	@ 1.60 GHz @ 1.95 GHz @ 2.10 GHz		+21.5 +21.4 +21.8		dBm dBm dBm
Stability (Note 3)	μ1, μ2, Κ, Β	Up to 18 GHz, -40 °C to +85 °C		>1		-
DC Specifications						
Supply voltage	Vdd			5		V
Quiescent current	lod	RBIAS = $6.2 \text{ k}\Omega$		105		mA

**Note 1:** Performance is guaranteed only under the conditions listed in this Table.

Note 2: Circuit topology optimized for best compromise between NF, S11, IIP3, and IP1dB.

Note 3: Applies to typical application circuit and components shown in Figure 26.

Note 4: Loss from input SMA connector and Evaluation Board up to pin 3 of device has been de-embedded (0.04 dB @ 1.95 GHz) from the NF measurement.

Parameter	Symbol	Test Conditions	Minimum	Typical	Maximum	Units
RF Specifications						
Noise Figure (Note 4)	NF	@ 1.60 GHz @ 1.95 GHz @ 2.10 GHz		0.85 0.91 1.02		dB dB dB
Small signal gain	IS21I	@ 1.60 GHz @ 1.95 GHz @ 2.10 GHz		19.0 18.3 17.4		dB dB dB
Input return loss	IS11I	@ 1.60 GHz @ 1.95 GHz @ 2.10 GHz		8 20 13		dB dB dB
Output return loss	IS22I	@ 1.60 GHz @ 1.95 GHz @ 2.10 GHz		10.0 13.0 11.5		dB dB dB
Reverse isolation	S12	@ 1.60 GHz @ 1.95 GHz @ 2.10 GHz		34.0 32.5 33.5		dB dB dB
3 <sup>rd</sup> Order Input Intercept Point	IIP3	$\Delta f = 1 MHz,$ $P_{IN} = -20 dBm/tone:$ @ 1.60 GHz @ 1.95 GHz @ 2.10 GHz		+12.5 +14.4 +15.0		dBm dBm dBm
3 <sup>rd</sup> Order Output Intercept Point	OIP3	$\Delta f = 1$ MHz, $P_{IN} = -20$ dBm/tone: @ 1.60 GHz @ 1.95 GHz @ 2.10 GHz		+31.5 +32.7 +32.4		dBm dBm dBm
Input 1dB Compression Point	IP1dB	@ 1.60 GHz @ 1.95 GHz @ 2.10 GHz		+3.0 +3.2 +5.4		dBm dBm dBm
Output 1dB Compression Point	OP1dB	@ 1.60 GHz @ 1.95 GHz @ 2.10 GHz		+21.0 +20.5 +21.8		dBm dBm dBm
Stability (Note 3)	μ1, μ2, Κ, Β	Up to 18 GHz, –40 °C to +85 °C		>1		-
DC Specifications						
Supply voltage	Vdd			5		۷
Quiescent current	lod	Rbias = 12 k $\Omega$		45		mA

Table 5. SKY67221-11 Electrical Characteristics (Note 1) (Note 2) (Note 3) (Vod = VBIAS = 5 V Nominal, Iod = 45 mA, TA = +25 °C, Characteristic Impedance [Zo] = 50  $\Omega$ , Unless Otherwise Noted)

**Note 1:** Performance is guaranteed only under the conditions listed in this Table.

Note 2: Circuit topology optimized for best compromise between NF, S11, IIP3, and IP1dB.

Note 3: Applies to typical application circuit and components shown in Figure 26.

Note 4: Loss from input SMA connector and Evaluation Board up to pin 3 of device has been de-embedded (0.04 dB @ 1.95 GHz) from the NF measurement.

## **Typical Performance Characteristics @ IDD = 85 mA**

(VDD = VBIAS = 5 V Nominal, TA = +25 °C, Characteristic Impedance [Zo] = 50  $\Omega$ , Unless Otherwise Noted)

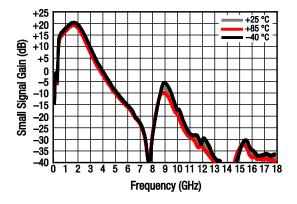


Figure 3. Broadband Gain Response vs Frequency Over Temperature

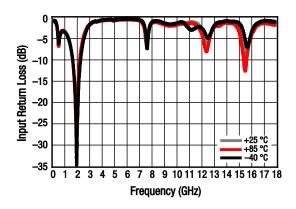


Figure 5. Broadband Input Return Loss vs Frequency Over Temperature

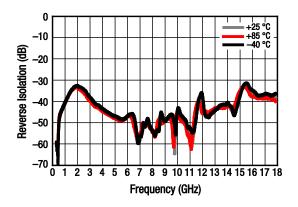


Figure 7. Broadband Reverse Isolation vs Frequency Over Temperature

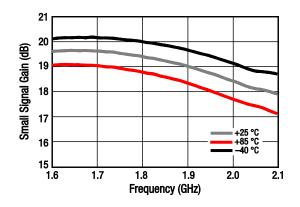


Figure 4. Narrowband Gain Response vs Frequency Over Temperature

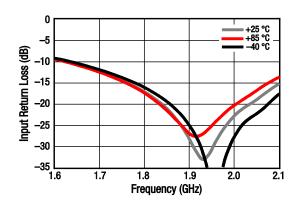


Figure 6. Narrowband Input Return Loss vs Frequency Over Temperature

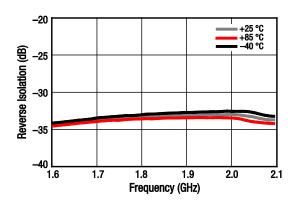


Figure 8. Narrowband Reverse Isolation vs Frequency Over Temperature

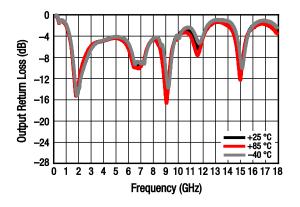


Figure 9. Broadband Output Return Loss vs Frequency Over Temperature

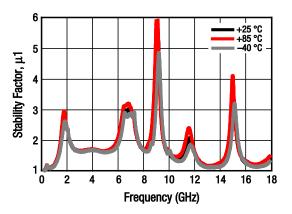


Figure 11. Stability Factor ( $\mu$ 1) vs Frequency Over Temperature

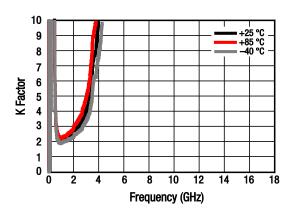


Figure 13. Stability Factor (K) vs Frequency Over Temperature

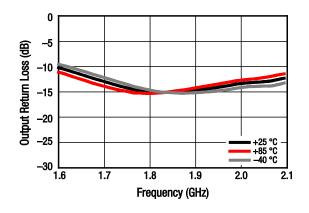


Figure 10. Narrowband Output Return Loss vs Frequency Over Temperature

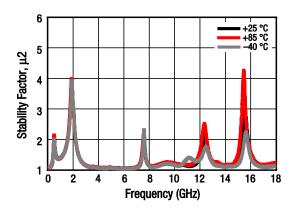


Figure 12. Stability Factor (µ2) vs Frequency Over Temperature

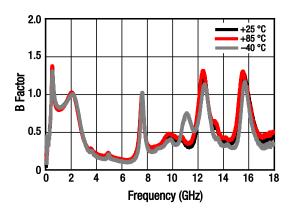


Figure 14. Stability Factor (B) vs Frequency Over Temperature

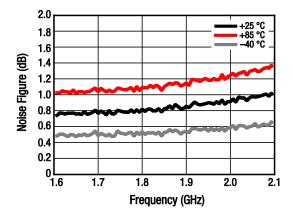


Figure 15. Noise Figure vs Frequency Over Temperature

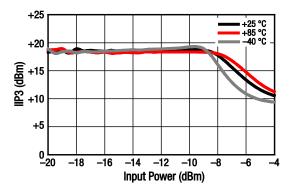
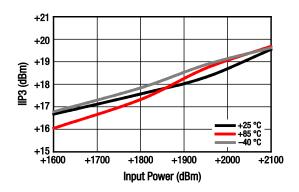


Figure 17. IIP3 vs Input Power Over Temperature @ 1950 MHz (Tone Spacing = 1 MHz)





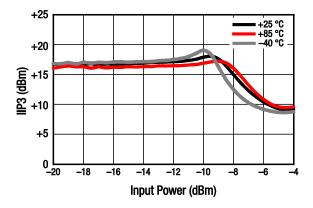


Figure 16. IIP3 vs Input Power Over Temperature @ 1600 MHz (Tone Spacing = 1 MHz)

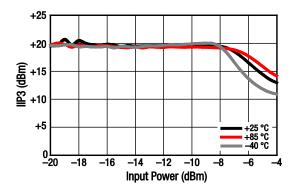


Figure 18. IIP3 vs Input Power Over Temperature @ 2100 MHz (Tone Spacing = 1 MHz)

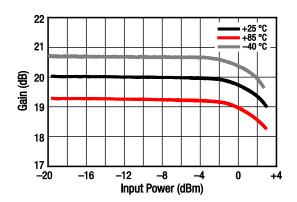


Figure 20. Gain vs Input Power Over Temperature @ 1600 MHz

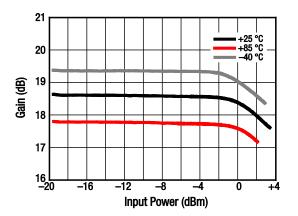


Figure 21. Gain vs Input Power Over Temperature @ 1950 MHz

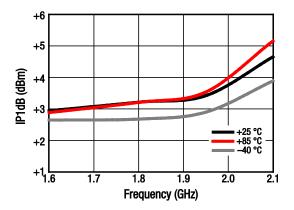


Figure 23. IP1dB vs Frequency Over Temperature

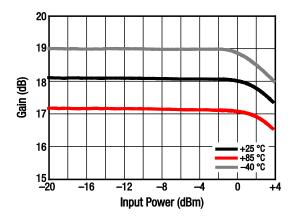


Figure 22. Gain vs Input Power Over Temperature @ 2100 MHz

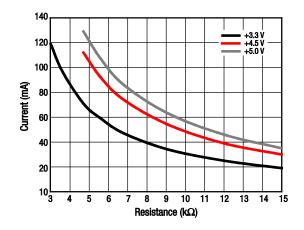


Figure 24. Resistor R1 vs Current Over Voltage

# **Evaluation Board Description**

The SKY67221-11 Evaluation Board is used to test the performance of the SKY67221-11 LNA. The Evaluation Board schematic diagram is shown in Figure 25. An assembly drawing for the Evaluation Board is shown in Figure 26. The layer detail physical characteristics are noted in Figure 27. Table 7 provides the Bill of Materials (BOM) list for Evaluation Board components.

# **Package Dimensions**

The PCB layout footprint for the SKY67221-11 is shown in Figure 28. Typical case markings are shown in Figure 29. Package dimensions for the 16-pin MCM are shown in Figure 30, and tape and reel dimensions are provided in Figure 31.

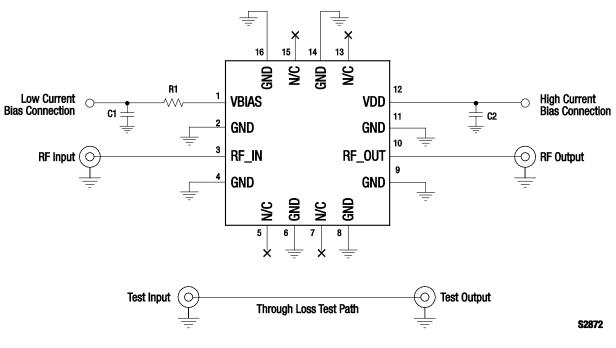


Figure 25. SKY67221-11 Schematic Diagram

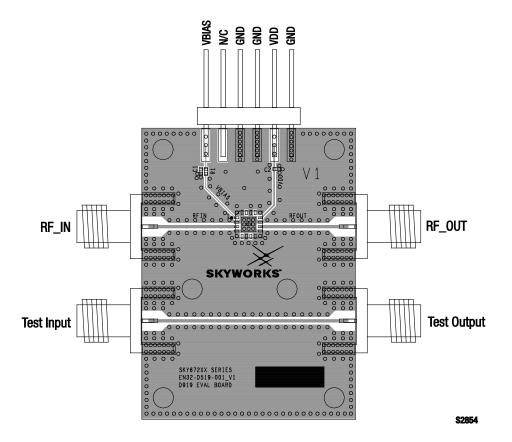
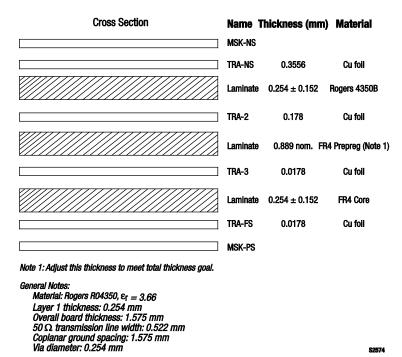


Figure 26. SKY67221-11 Evaluation Board Assembly Drawing



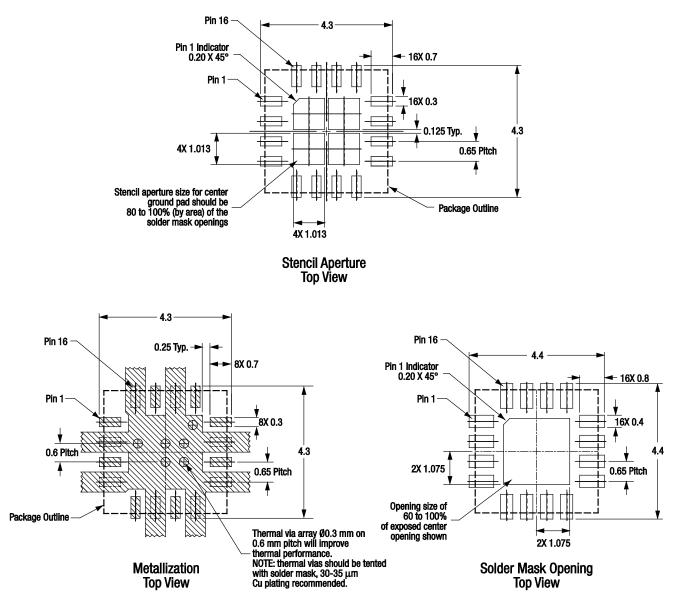
S2574

#### Figure 27. Layer Detail Physical Characteristics

#### Table 6. SKY67221-11 Evaluation Board Bill of Materials

Component	Size	Value	Vendor	Part Number
C1		DNI		
C2		DNI		
R1 for 85 mA operation (Note 1)	0402	6800 Ω	Panasonic	

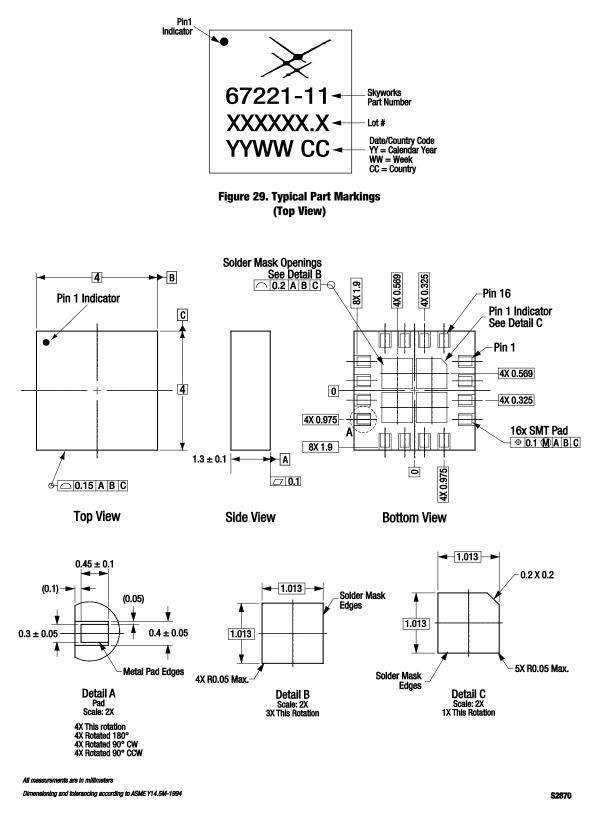
Note 1: Placement in relation to component package is not critical.



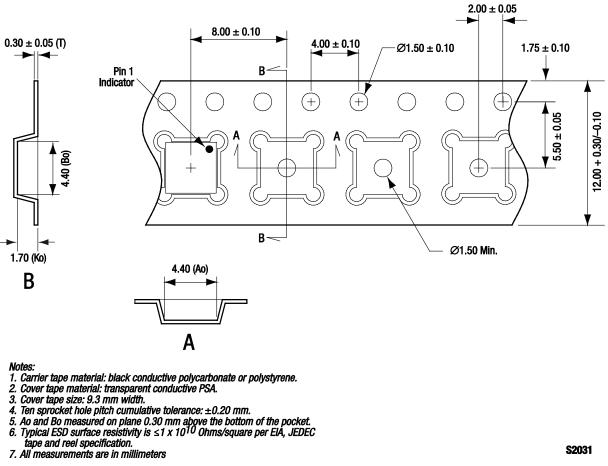
All dimensions are in millimeters

S2869

Figure 28. SKY67221-11 PCB Layout Footprint









S2031

### **Ordering Information**

Model Name	Manufacturing Part Number	Evaluation Board Part Number
SKY67221-11 1.6-2.1 GHz LNA Module	SKY67221-11	EN32-D519-001_V1

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